Translation

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November 10, 2026

FUJIMI INCORPORATED
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Notice Concerning the Detailed Version of the Medium- to Long-Term Business Plan 2026

FUJIMI INCORPORATED (the "Company") hereby announces that the detailed version of a new 6-year business plan, (the "Plan"), covering the period beginning with the fiscal year ending March 2027.

The quantitative aspects of the Plan were announced on October 9, 2026.

(Note) Cautionary Statement Regarding Forward-Looking Statements

The forward-looking statements contained in this document, including business performance forecasts, are based on judgments and assumptions derived from information currently available. Therefore, please be aware that actual results may differ from these forecasts due to various factors.

- End -

Medium- to Long-Term Business Plan 2026

(FY2027 – FY2032)

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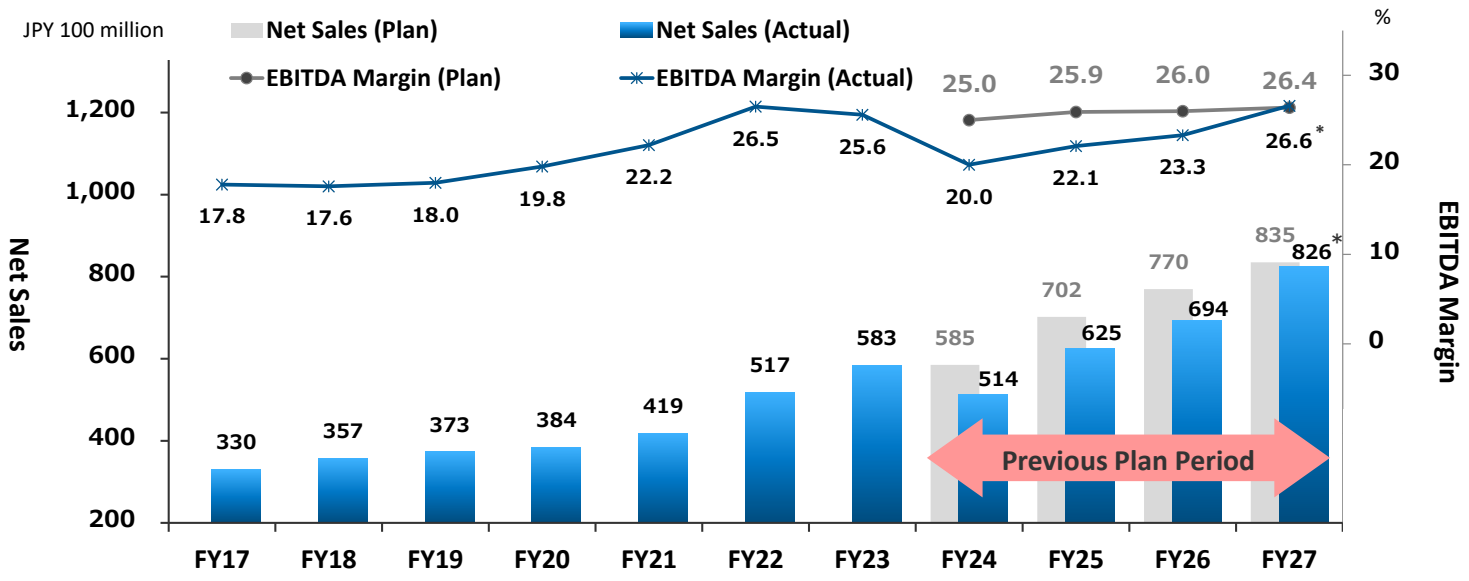
Contents

- ▷ Review of Medium- to Long-Term Business Plan 2023 (Previous Plan): P.3 – P.11
- ▷ Medium- to Long-Term Business Plan 2026 (New Plan): P.12 – P.32

Review of Medium- to Long-Term Business Plan 2023 (FY2024-)

Review of the Previous Plan: Highlights

Following an initial decline in net sales and EBITDA margin due to the post-COVID demand correction, performance recovered as AI and semiconductor demand expanded, with FY2027 results expected to nearly achieve the original targets.



*FY27: Forecast as of November 5, 2026

Review of the Previous Plan: Quantitative Targets

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The FY2027 net sales and EBITDA margin targets are now expected to be nearly achieved.

Target	FY2026		FY2027		
	Year 3 of Plan 2023 (Previous Plan)		Year 4 of Plan 2023 (Previous Plan)		
	Plan 2023 (Previous Plan)	Actual	Plan 2023 (Previous Plan)	Plan 2026 (New Plan)	Forecast (as of Nov. 5)
Net Sales (JPY 100 million)	770	694	835	825	826
New Businesses as % of Net Sales	15.0%	4.3%	-	4.2%	4.2%
Non-Semiconductor Businesses as % of Net Sales	20.0%	16.6%	19.9%	15.3%	15.3%
Non-Polishing Businesses as % of Net Sales	8.0%	5.1%	-	3.9%	3.9%
EBITDA Margin[*1]	26.0%	23.3%	26.4%	26.2%[*3]	26.6%
ROE[*2]	15.0%	11.3%	15.0%	14.3%	14.7%

*1 EBITDA Margin = (Operating Income + Depreciation) / Net Sales x 100
*2 ROE = Net Income / Equity x 100
*3 Revised to 26.2% from the 26.0% disclosed on October 9, 2026

Blue: Target Achieved Red: Below Target

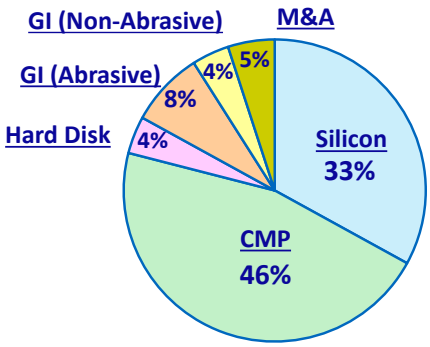
Review of the Previous Plan: Sales by Application

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CMP and **General Industry (Non-Abrasive)** outperformed the Plan, while **Silicon, Hard Disk, General Industry (Abrasive), and M&A** underperformed.

As sales for advanced semiconductor applications expanded, the sales mix of CMP increased more than originally planned.

FY2026 Plan

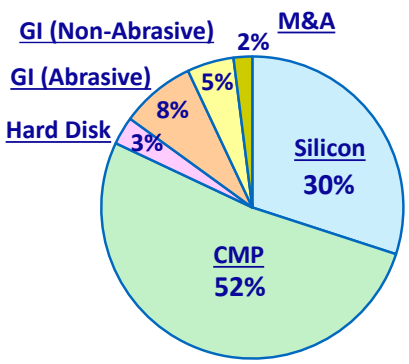


JPY 100 million (amounts less than JPY 100 million are rounded down)

	FY2026		
	Plan2023 (Previous Plan)	Actual	Variance
CMP	354	361	+7
Silicon	254	210	-44
Hard Disk	31	22	-9
General Industry (GI) —Abrasive	62	51	-11
General Industry (GI) —Non-Abrasive	31	34	+3
M&A	39	14	-25
Total	770	694	-76

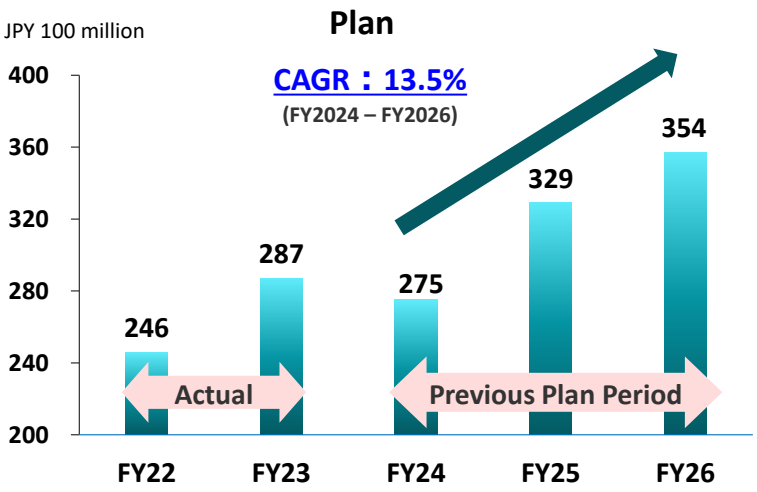
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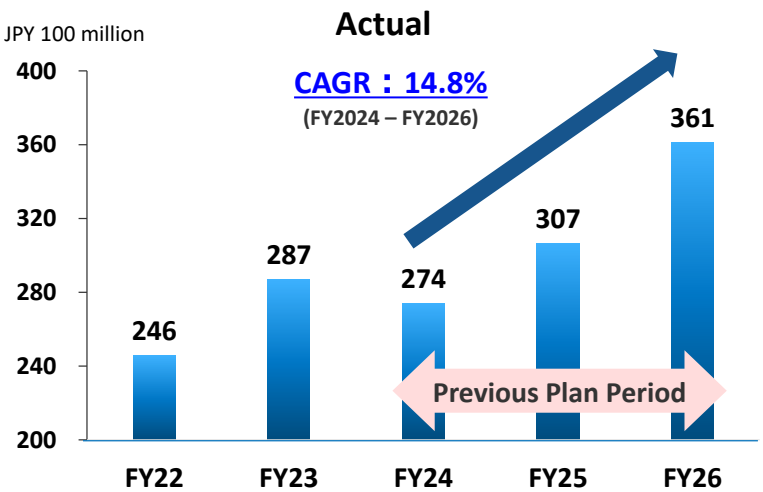
FY2026 Actual



Review of the Previous Plan: CMP

Sales of CMP products achieved a CAGR of 14.8%, outperforming the Plan, driven by increased adoption in advanced logic and memory semiconductor applications.





Review of the Previous Plan: Initiatives and Achievements by Business

Semiconductor

Category	Vision	Strategic Initiatives	Achievements
CMP	Top of the world's premier manufacturer of FEOL slurry	Establishment of quality and technology that meet the expectations from leading customers, and maximization of the strengths through network covering Japan, the U.S., and Taiwan	Maintained a leading global market share in FEOL slurries (estimated at over 50%)
Packaging	Acquire business opportunities in the field of materials for semiconductor packaging	Promoting tailored product development for each customer in response to advanced packaging technology	Won new business in multiple applications and drove mass production expansion
Silicon	Leading manufacturer of abrasives for silicon wafers	Providing tailored polishing process solution for each customer by establishing proprietary technologies (raw material design, blending and refining technologies)	-Advanced raw material purification, formulation, and material design -Maintained a dominant global market share in lapping abrasives and polishing slurries
SiC	Major supplier of abrasives for SiC power semiconductors	Expanding market share by establishing new technologies based on our core technologies and introducing new products with high efficiency	-Product adoption progressed, but market growth was delayed by slower-than-expected EV adoption -Continued development aligned with customer needs, including larger-diameter wafers for AI applications

Review of the Previous Plan: Initiatives and Achievements by Business

Non-Semiconductor

Category	Vision	Strategic Initiatives	Achievements
Thermal Spray	Expanding market share	Creating customer value by providing solutions using composite technologies (Semiconductor) Establish status as a partner developing product for advanced semiconductor manufacturing equipment (Non-semiconductor) Identification and acquisition of new promising projects that will become pillars of our business	-Expanded business across semiconductor, industrial machinery, and automotive sectors -Proposed new rare-earth-free thermal spray materials to key customers -Began establishing a risk-diversified supply chain
Hard Disk	Returning to top player by regaining market share	Strengthen product competitiveness by enhancing development capabilities and improving technical support systems for customers	-Advanced raw material purification, formulation, and material design, laying the groundwork for further market share gains -Overall sales recovered as market conditions improved
Polishing Solutions	Creation of new business in the polishing solutions area	Providing advanced polishing solutions to satisfy customers' needs, including automotive polishing compounds	-Launched a contract processing business -Won new business for compound semiconductor slurries used in optoelectronic devices, a key technology supporting AI demand
Advanced Technologies & Functional Materials	Creation of new business in the powder area	Continue development and commercialization of functional materials (ceramic powders, ceramic composite materials, new powders, etc.) using unique technical marketing and powder technologies	Customers are evaluating the following new powder technologies and products: ・Thermally conductive fillers ・Ceramic composite materials ・New powders in plate-like and spherical forms ・Cemented carbide materials for 3D printing

Review of the Previous Plan: CAPEX

- Capital expenditures exceeded the Plan due to rising material and construction costs, as well as earlier-than-planned orders for long lead-time items driven by strong future demand.
- Capital expenditures substantially increased beyond the Plan to expand the Kakamiyama Plant, construct new plants adjacent to the Kakamiyama Plant and in Taiwan, and introduce state-of-the-art facilities and equipment for R&D to meet growing semiconductor demand, particularly for AI-related applications.

CAPEX

(JPY 100 million)

	Previous Plan	Actual/ New Plan	Variance
FY24-26 3-Year Total	300	388 (Actual)	+88
FY27-29 3-Year Total	250	850 (New Plan)	+600
Total	550	1,238	+688

See page 28 for a detailed variance analysis.

Review of the Previous Plan: Conclusions

- The FY2027 KPI targets for net sales and EBITDA margin are now expected to be nearly achieved.
- Driven by the recovery in semiconductor demand, particularly for AI-related applications, and expectations of continued strong demand, capital expenditures are projected to increase substantially compared with the Medium- to Long-Term Business Plan 2023. However, considering the time required for construction, equipment installation, and customer qualification, **these investments are expected to be recovered after FY2032, beyond the period covered by the Medium- to Long-Term Business Plan 2026.**
- While the Medium- to Long-Term Business Plan 2023 assumed that capital expenditures would be funded entirely from internal resources, **external financing will be required** to cover the funding shortfall resulting from the substantial increase in capital expenditures.

Growing demand for AI semiconductors, growing protectionism including frequent changes in U.S. tariff policies and China's export restrictions, geopolitical risks stemming from U.S. – China tensions and the deteriorating situation in the Middle East, longer lead times and higher procurement costs for energy and raw materials, and labor shortages and rising wages are significantly affecting our business environment.

Formulated the Medium- to Long-Term Business Plan 2026, covering the next six years

Medium- to Long-Term Business Plan 2026 (FY2027-)

Basic Policy

Based on its corporate mission, “We will develop new, innovative technologies and applications with a commitment to environmental sustainability, thereby enabling the advancement of technology for the betterment of humanity,” Fujimi's basic policy is to evolve from an abrasives manufacturer into a “Powder & Surface” company through the further expansion of its existing businesses, including semiconductor-related businesses, and the creation of new businesses that will serve as future growth drivers, contributing to the realization of a sustainable society.

Under the new six-year Business Plan covering FY2027 through FY2032, Fujimi aims to capture future growth opportunities and establish a supply system that supports customers' long-term business expansion amid growing demand for semiconductor-related products and rising capacity utilization.

To achieve these objectives, Fujimi will focus on:

- Making proactive and continuous investments in production and R&D infrastructure ahead of future demand.
- Building a resilient business foundation adaptable to a changing business environment.
- Strengthening investments in human capital and ESG initiatives as the foundation of sustainable management.

Through these initiatives, Fujimi aims to realize its medium- to long-term corporate slogan, "We support your forward-looking ideas and challenges.“

Environmental Analysis

- The semiconductor market is expected to grow during the new Business Plan period, driven by advances in AI performance and its widespread adoption.
- However, the semiconductor market has historically been cyclical, making the cultivation of non-semiconductor businesses essential to our sustainable growth.

Macro Trends	Semiconductor Industry	Impact on Our Business
Growing Demand for AI and Data Centers	▷ Rapid growth in demand for advanced logic and memory chips, accompanied by a sharp increase in power consumption ▷ Advances in semiconductor performance through finer process nodes in front-end process and chip stacking and high-density interconnections in back-end process ▷ Accelerating investment in capacity expansion by major semiconductor manufacturers	▷ Strengthening our new product development capabilities is essential to respond quickly and effectively to increasingly sophisticated and diverse customer requirements for leading-edge semiconductors. ▷ Growing demand for our products for optoelectronic devices, which contribute to reducing power consumption in data centers ▷ Expansion of business opportunities in front-end process and new opportunities in back-end process ▷ Further expansion of production capacity is essential to maintain a stable supply amid growing demand for our polishing materials.
Rising Geopolitical Risks	▷ Increasing instability in global supply chains ▷ Rising prices driven by surging crude oil prices	▷ Strengthening our stable supply capabilities is essential. ▷ Rising costs of raw materials, auxiliary materials, construction, energy, and other inputs
Addressing Environmental Challenges	▷ Greater emphasis on environmental initiatives throughout the supply chain to achieve a decarbonized society	▷ Responding to new and revised environmental regulations and differing regulatory requirements across countries and regions is essential.

New Medium- to Long-Term Business Plan: Quantitative Targets

FUJIMI INCORPORATED

- Leverage large-scale investments (CAPEX totaling JPY 130 billion) to capture growth in the semiconductor market, increase revenue, and maintain profitability despite increased depreciation expenses.

Metric	Actual	Year 1 of the Plan	Year 3 of the Plan	Year 6 of the Plan
	FY2026	FY2027	FY2029	FY2032
(JPY 100 million) Consolidated Net Sales	694	825	1,040	1,380
New Business Sales Ratio	4.3%	4.2%	11%	14%
Operating Income Margin	19.9%	20.9%	20%	21%
EBITDA Margin	23.3%	26.2%*	29%	31%
ROE	11.3%	14.3%	14%	17%

Net Sales:
Target a CAGR of 9% from the first year of the Plan, and a new business sales ratio of 14%

Profitability:
Aim to improve the EBITDA margin despite a temporary decline in the operating income margin due to increased depreciation and R&D expenses

Capital Efficiency:
Target ROE of 17% or higher in FY2032

Dividend Policy

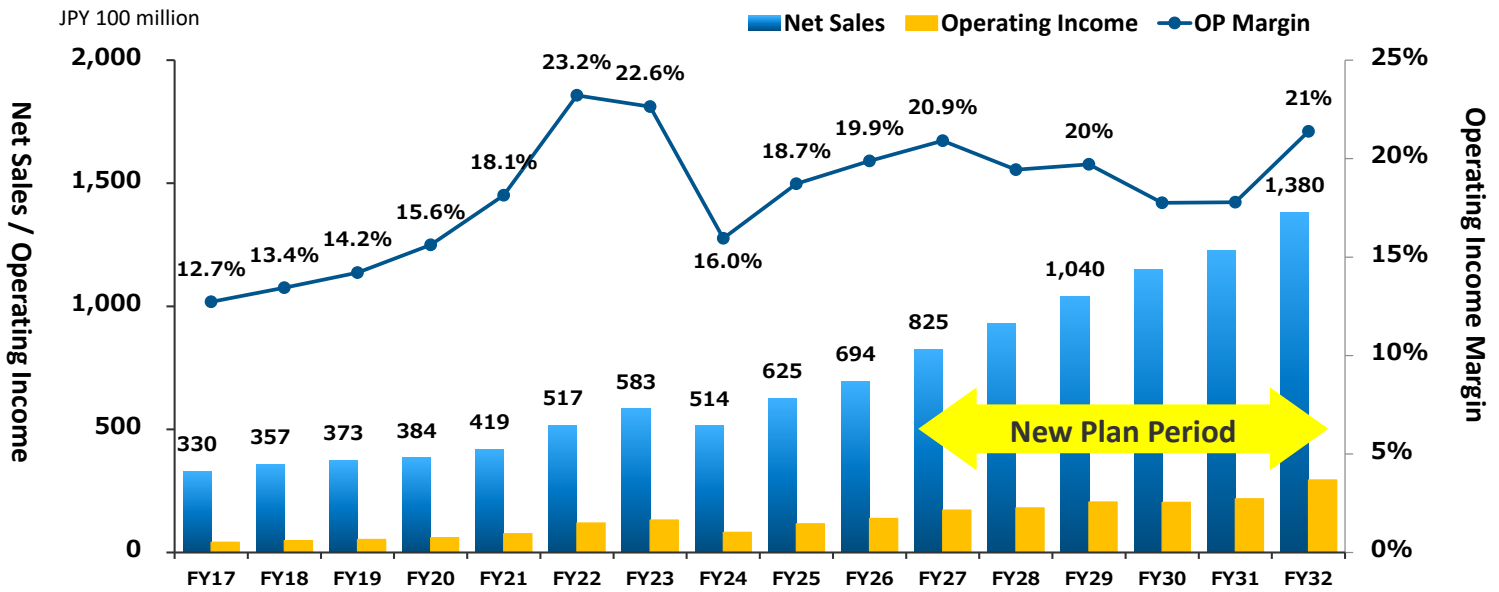
- Target a consolidated dividend payout ratio of 55% or higher
- Maintain a progressive dividend policy through FY2029
- For FY2030 onward, we will review our dividend policy to achieve a long-term balance between sustainable growth through investment and shareholder returns.

* Revised to 26.2% from the 26.0% disclosed on October 9, 2026

New Medium- to Long-Term Business Plan: Highlights

FUJIMI INCORPORATED

- We aim to achieve sustainable sales growth by steadily capturing business opportunities, targeting net sales of JPY 138 billion in FY2032.
- Operating income and margin are expected to decline temporarily due to increased depreciation expenses from major capital investments, but margin is projected to rise again in FY2032 as depreciation growth levels off.



Key Initiatives

Based on our basic policy, the key initiatives to be undertaken during the new Business Plan period are as follows:

1. Creation of New Businesses that Realizes Evolution from an Abrasives Manufacturer to "Powder & Surface" Company

- ✓ Strengthen marketing system by leveraging the strengths of proprietary technologies
- ✓ Providing original, high value-added products in functional materials
- ✓ Providing process solutions to help customer create the desired surface
- ✓ Promote M&A to create new businesses and acquire technologies necessary for growth

2. Building a Robust Foundation for Semiconductor-Related Businesses and Establishing an Overwhelming Position in the Field of Materials for Next Generation Semiconductors

- ✓ Execute large-scale investments globally and ensure their successful ramp-up to meet medium- to long-term growth in the semiconductor market
- ✓ Capture leading-edge business opportunities by maintaining and enhancing industry-leading R&D and quality assurance capabilities
- ✓ Develop materials for advanced packaging substrates to enable next-generation semiconductors with higher performance and greater functionality, and win new business
- ✓ Explore and capture new business opportunities in the evolving AI and semiconductor sectors

3. Reinforcement of Core Technology and Development of New Technology

- ✓ Further development of core technologies (filtration, classification, and purification technologies, powder technology, and chemical technology)
- ✓ Challenge to develop innovative new technologies to create customer value

Key Initiatives

4. Building a Resilient Business Foundation through the Integration of Technology and Data, and Advanced Strategic Supply Chain Management

- ✓ Strengthen engineering capabilities by integrating technology and data, and prepare for and implement data-driven operations and decision-making
- ✓ Strengthen supply chains and business continuity through strategic supply chain management and enhanced risk management that account for geopolitical risks
- ✓ Enhance organizational agility and execution capabilities to anticipate changes in the business environment and respond to them quickly and flexibly

5. Challenge to Develop GRIT* Organization and Human Resource for Realization of a 100 Year Company

- ✓ Establishment of an unwavering integrity mindset to pass on pride in manufacturing excellence to the next generation
- ✓ Foster and realize a great work culture that motivates employees to excel
- ✓ Cultivation of professionals who fulfills customer's needs
- ✓ Creation of best teamwork by striving together

6. Implementation of Sustainability Management with a Focus on Materiality

- ✓ Proactive contribution to solve environmental issue, including climate change
- ✓ Strengthening of business continuity capabilities focusing risk management and supply chain management
- ✓ Strengthening of governance structure to support the global business activities
- ✓ Promotion of value-creating activities that contribute to improving sustainability

*GRIT: The perseverance and passion to pursue long-term goals and see them through despite challenges and setbacks.

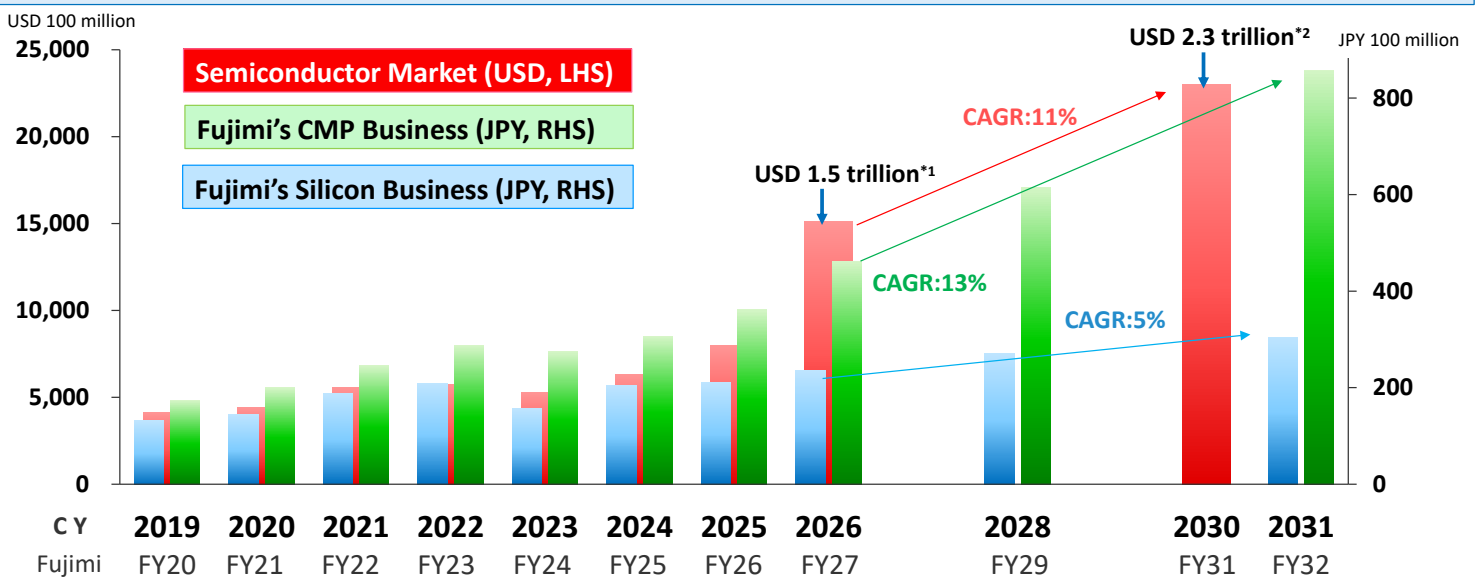
Initiatives by Business

	Category	Vision	Strategic Initiatives
Semiconductor	CMP (incl. Advanced Packaging)	Lead the FEOL slurry market and establish a strong presence in advanced packaging	-Expand new project opportunities through deeper customer engagement -Strengthen R&D capabilities and enhance customer responsiveness through the development of proprietary technologies
Semiconductor	Silicon	Lead the silicon wafer polishing materials market	Establish proprietary technologies in raw material design, formulation, and purification to deliver tailored polishing solutions
Semiconductor	Thermal Spray	-Leverage integrated technologies to address leading-edge customer needs -Gain market share through value-added solutions	Build customer trust through customer-focused sales and marketing, agile product development, a risk-diversified supply chain, and stable manufacturing operations that ensure a reliable supply
Non-Semiconductor	Hard Disk	Regain market share and return as a major player	Strengthen development capabilities in raw material design, formulation, and purification by leveraging accumulated technologies and expertise
Non-Semiconductor	Polishing Solutions	Expand business by leveraging best-in-class surface engineering solutions	Capture customers' surface engineering needs early and provide differentiated solutions by combining polishing materials with polishing and cleaning processes, leveraging proprietary technologies, expertise, and networks cultivated through our precision polishing materials business
Non-Semiconductor	Advanced Technologies & Functional Materials	Create and develop new businesses by delivering value through powder technologies	-Advance and expand powder technologies while promoting sales and marketing activities that accurately identify customer needs -Continuously propose new solutions and applications for emerging markets while addressing customer needs

Semiconductor Market and Our Related Businesses

*1 Source: WSTS, June 2, 2026
*2 Source: McKinsey, September 18, 2026

- The semiconductor market is expected to exceed USD 2.3 trillion by 2030, driven by demand for AI applications.
- We forecast demand for our semiconductor-related products based on customers' capacity expansion plans, factoring in expected reductions in the usage of our products.
- While the semiconductor market is projected to grow at a CAGR of 11% from CY2026 to CY2030, we expect CAGRs of 13% for our CMP products and 5% for silicon wafer products from FY2027 to FY2032.



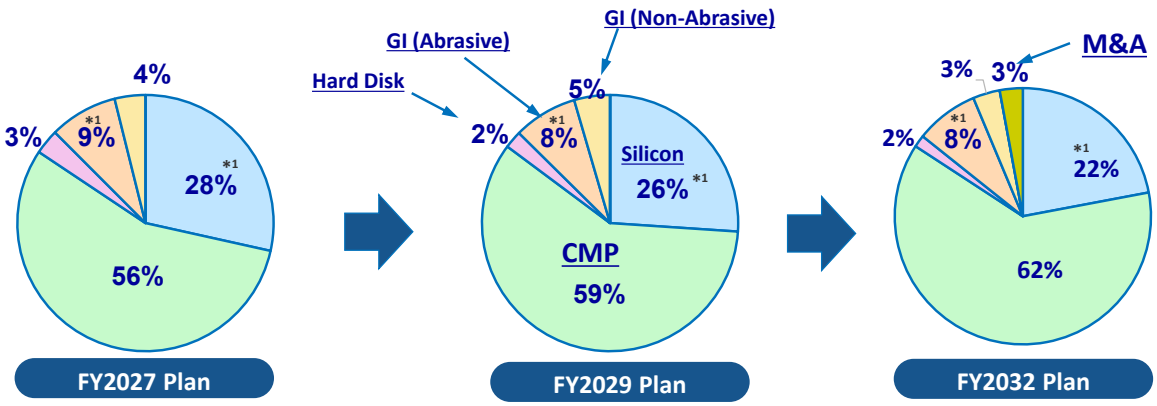
Sales by Application

(JPY 100 million)

	Year 1 of the Plan	Year 3 of the Plan	Year 6 of the Plan
	FY2027 Plan	FY2029 Plan	FY2032 Plan
Silicon	235*1	271*1	304*1
CMP	461	615	858
Hard Disk	26	23	21
General Industry (GI) – Abrasive	71*1	84*1	110*1
General Industry (GI) – Non-Abrasive	32	47	47
M&A*2	-	-	40

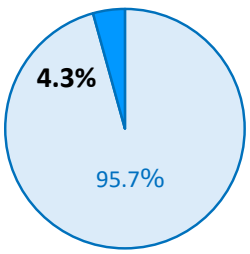
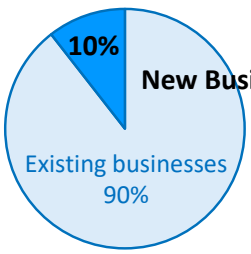
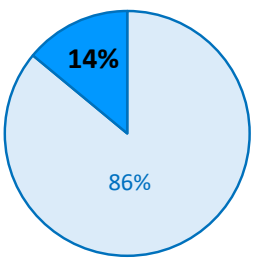
*1: Sales of Silicon and GI (Abrasive) have been revised from those in the October 9, 2026 disclosure to align with earnings disclosure categories. Approximately 1% of sales in each fiscal year was reclassified from Silicon to GI (Abrasive).

*2: Sales from Nanko, acquired on October 21, 2024, are included in GI: Abrasive, not in M&A.



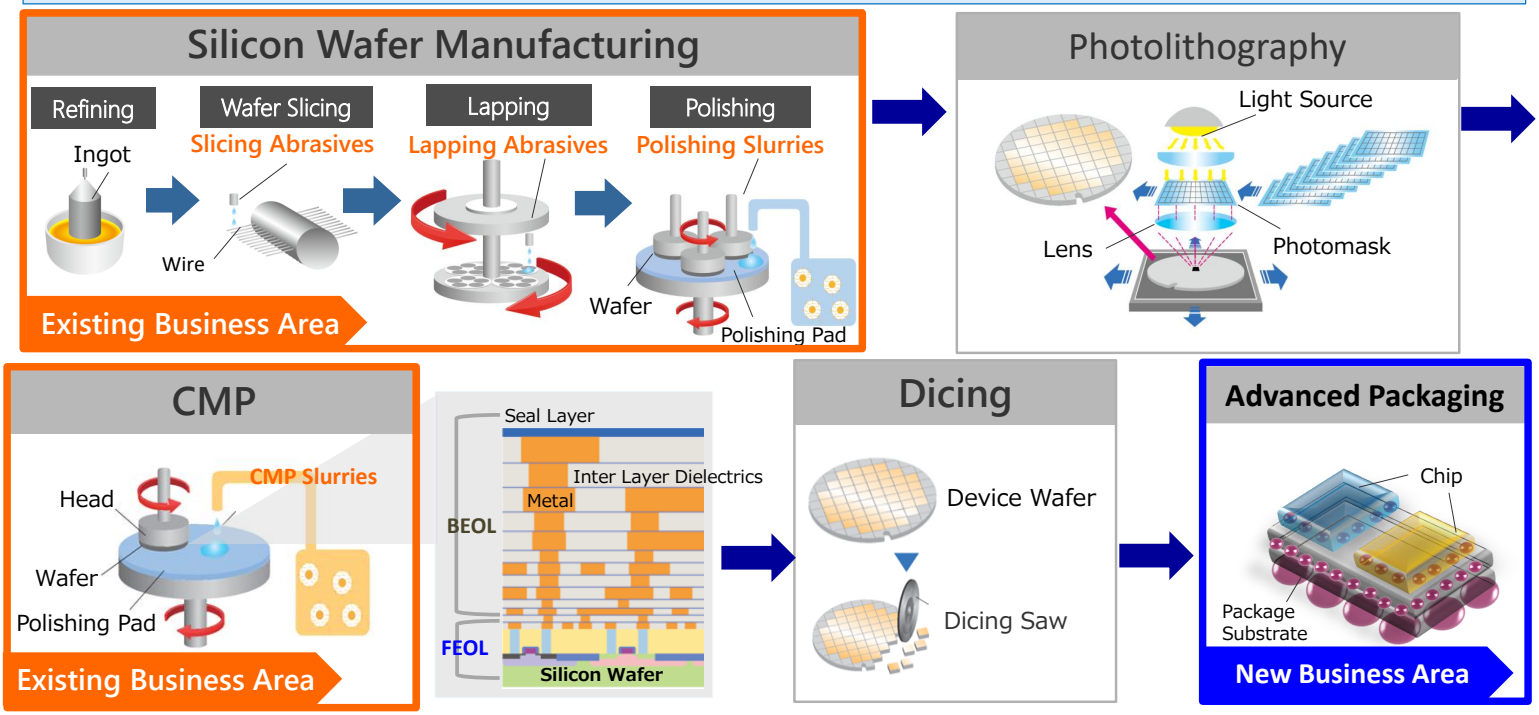
New Businesses as a Percentage of Total Sales

Building on the technological capabilities we have developed since our founding, we will flexibly adopt to changes in the business environment, capture new business opportunities, and steadily expand our new businesses.

	FY2026 Actual	FY2029 Plan	FY2032 Plan
New Businesses			
Growth Drivers	▻ **Semiconductor-Related**：Materials for advanced packaging, and optoelectronic devices ▻ **General Industry (Abrasive)**：Polishing compounds for automotive exteriors Contract processing ▻ **General Industry (Non-Abrasive)**： Ceramic powders (high flowability, high thermal conductivity, shape control) Ceramic composites (lightweight, high heat resistance) ▻ **M&A**		

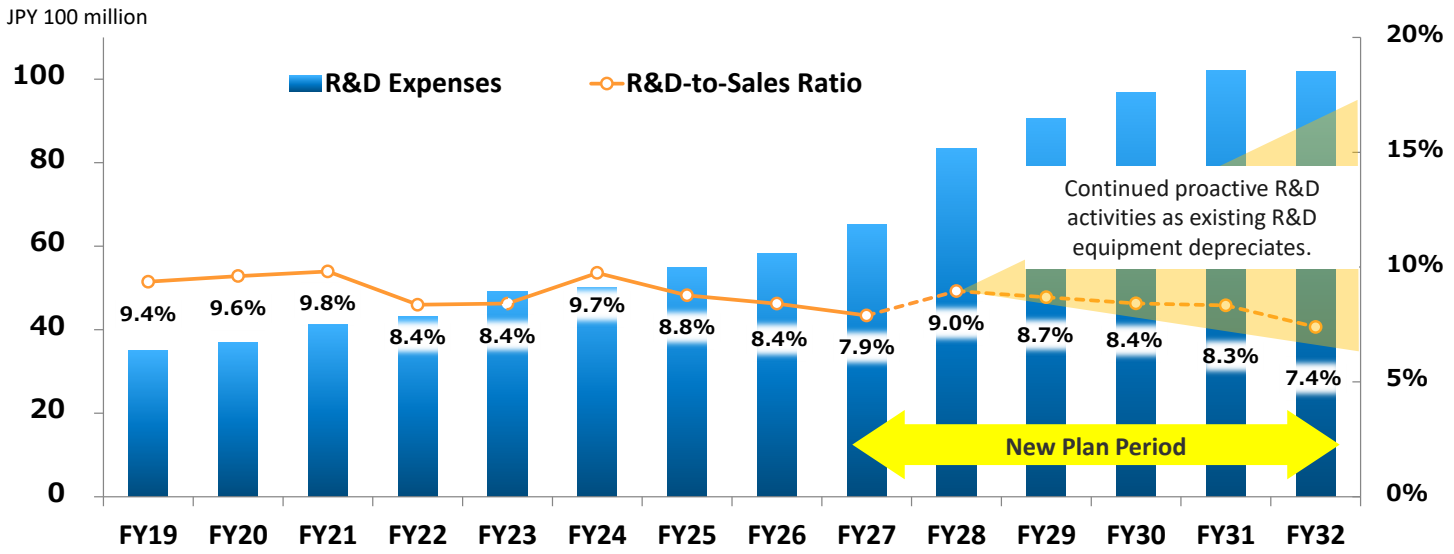
CMP Slurries for Advanced Packaging

In addition to silicon wafer manufacturing and CMP processes, we aim to achieve further growth by expanding into the advanced packaging market.



R&D Expenses

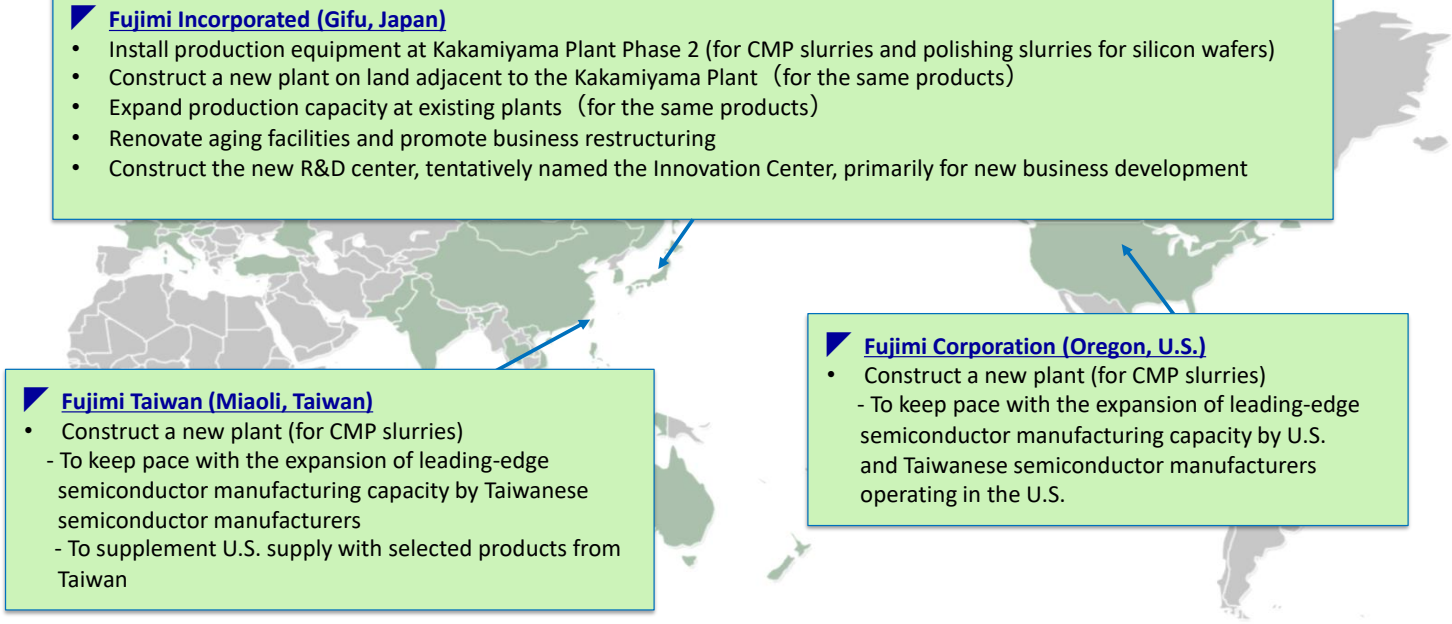
During the New Business Plan period, we will continue substantial R&D investment to meet customer needs through workforce expansion, upgrades to R&D facilities, installation of state-of-the-art equipment, and construction of a new R&D center. However, the R&D-to-sales ratio, which has historically been just under 10%, is expected to remain around 8% as sales increase.



Major Capital Investment Plans

As countries worldwide increasingly regard semiconductors as strategic assets and invest heavily in domestic production, we are responding by strengthening its R&D, manufacturing, and quality assurance capabilities across our operations in Japan, the U.S., and Taiwan.

Fujimi Incorporated (Gifu, Japan)
- Install production equipment at Kakamiyama Plant Phase 2 (for CMP slurries and polishing slurries for silicon wafers)
- Construct a new plant on land adjacent to the Kakamiyama Plant （for the same products）
- Expand production capacity at existing plants （for the same products）
- Renovate aging facilities and promote business restructuring
- Construct the new R&D center, tentatively named the Innovation Center, primarily for new business development



Fujimi Taiwan (Miaoli, Taiwan)
- Construct a new plant (for CMP slurries)
  - To keep pace with the expansion of leading-edge semiconductor manufacturing capacity by Taiwanese semiconductor manufacturers
  - To supplement U.S. supply with selected products from Taiwan

Fujimi Corporation (Oregon, U.S.)
- Construct a new plant (for CMP slurries)
  - To keep pace with the expansion of leading-edge semiconductor manufacturing capacity by U.S. and Taiwanese semiconductor manufacturers operating in the U.S.

Capital Investment Plan

The semiconductor market is expected to see continued growth and technological advancement, particularly in advanced applications such as AI. To capture future growth opportunities and support our customers' medium- to long-term business expansion, it is essential to proactively and continuously strengthen our manufacturing and R&D infrastructure rather than waiting for demand to materialize.

The planned capital expenditures are not merely intended to address near-term demand growth, but are essential strategic investments to ensure long-term supply stability, maintain and enhance our technological competitiveness, and achieve sustainable growth over the medium to long term.

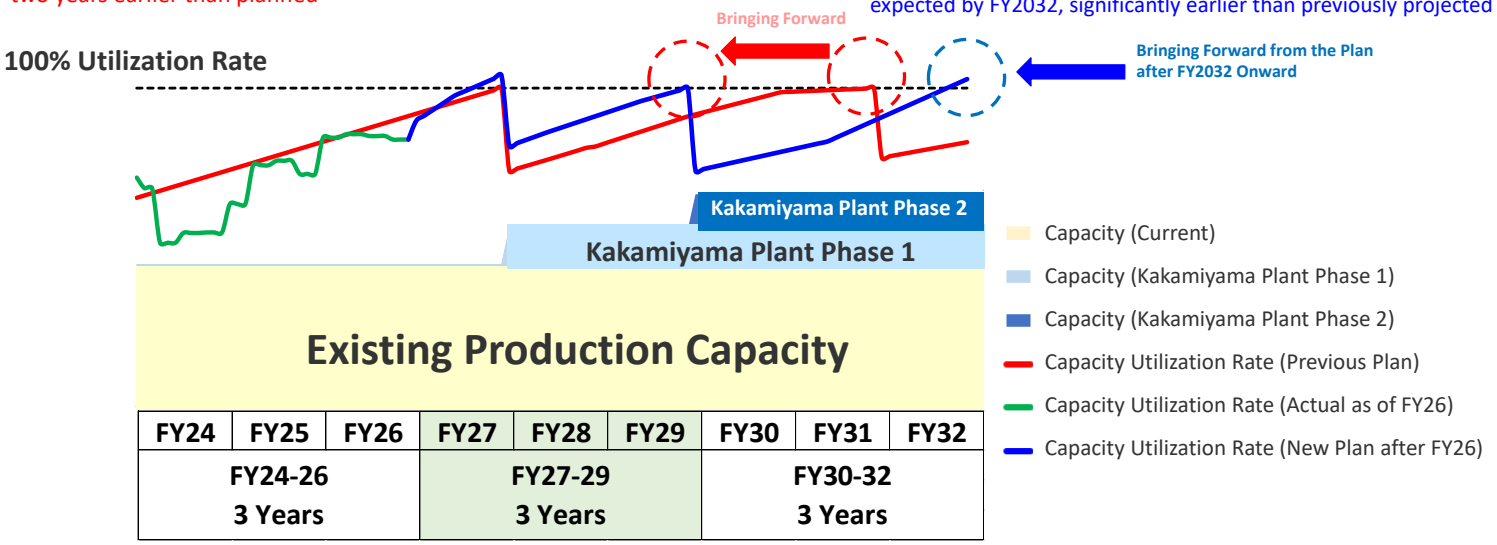
	FY2024 – FY2026 3-Year Total (Actual)	FY2027 – FY2032 (Plan)		
		FY2027 – FY2032 6-Year Total	FY2027 – FY2029 3-Year Total	FY2030 – FY2032 3-Year Total
(JPY 100 million) CAPEX	388	1,300	850	450

Growing Mid- to Long-Term Demand and Capacity Utilization

- Through FY2027: Increasing utilization of existing production capacity to meet demand
- FY2028: Start-up of the Kakamiyama Plant Phase 1, easing capacity constraints
- Bringing forward investments, including the Kakamiyama Plant Phase 2, required to support growing demand beyond FY2028

1. Bringing Forward Investment in the Kakamiyama Plant Phase 2:
Phase 1 capacity at the Kakamiyama Plant expected to reach full utilization two years earlier than planned

2. Bringing Forward Investment in the Site Adjacent to the Kakamiyama Plant:
Full utilization of the Kakamiyama Plant capacity, including Phase 2, expected by FY2032, significantly earlier than previously projected



FY24	FY25	FY26	FY27	FY28	FY29	FY30	FY31	FY32
FY24-26 3 Years			FY27-29 3 Years			FY30-32 3 Years		

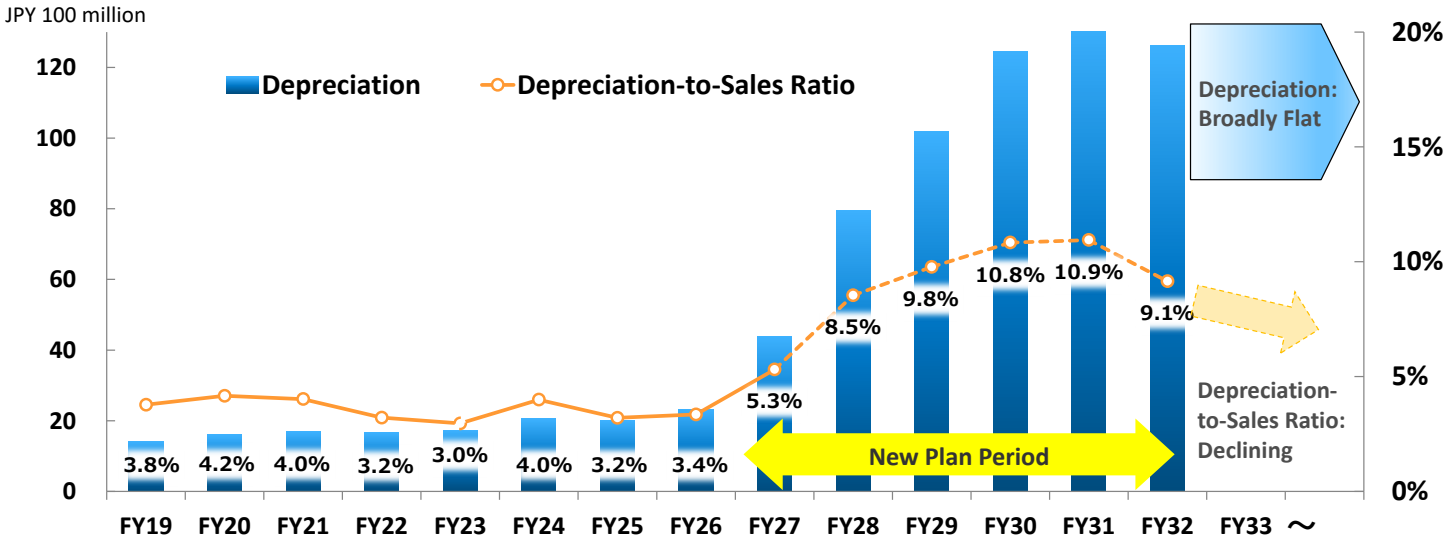
Capital Expenditure Variance Analysis

- Capital expenditures exceeded the plan due to rising material and construction costs, as well as earlier-than-planned orders for long lead-time items driven by strong future demand.
- Capital expenditures were substantially increased beyond the Previous Plan to expand the Kakamiyama Plant, construct new plants adjacent to the Kakamiyama Plant and in Taiwan, and introduce advanced equipment for R&D to meet growing semiconductor demand, particularly in AI-related applications.

	Previous Plan	Actual/ New Plan	Variance	Key Factors	
(JPY 100 million) FY24-26 3-Year Total	300	388 (Actual)	+88	1. Plant construction projects brought forward due to increased demand and longer lead times	+40
				2. Higher-performance production equipment for advanced semiconductors	+30
				3. Rising constructions costs for the new plant and R&D center	+50
				4. Review and reduction of other capital investments	-30
FY27-29 3-Year Total	250	850 (New Plan)	+600	1. Plant construction projects brought forward to FY2024 - FY2026	-40
				2. Plant construction projects originally scheduled for FY2030 onward brough forward	+170
				3. Additional plant construction in Taiwan to meet growing demand	+200
				4. Equipment upgrades, efficiency improvements, IT investments, plant restructuring, and others	+270
Total	550	1,238	+688		

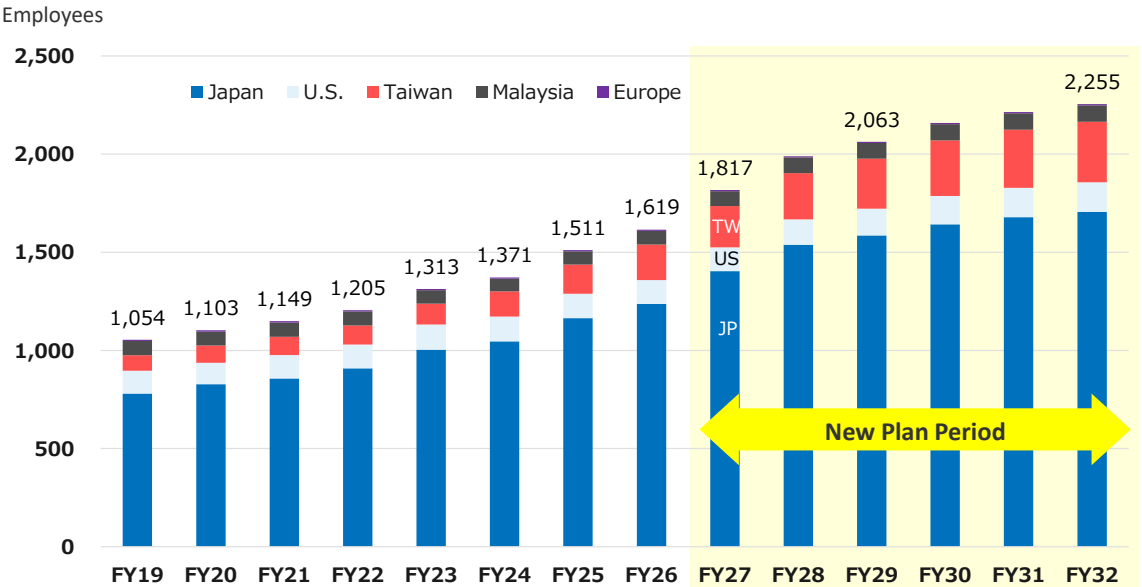
Depreciation

- The depreciation-to-sales ratio, historically at 3-5%, is expected to rise significantly from FY2027, driven by investments in new plants, expanded production capacity, enhanced R&D facilities, advanced equipment, and the new R&D center to strengthen core technologies and develop new technologies.
- From FY2033 onward, **depreciation is expected to remain broadly flat**, as decreases from existing assets offset increases from new investments, while **the depreciation-to-sales ratio is expected to decline** as sales grow.



Headcount and Workforce Plan

- Increase headcount in Japan and Taiwan, where new plants are planned to support business expansion.
- Expand R&D headcount in Japan, the U.S., and Taiwan to capture new business opportunities.



*The above headcount includes temporary employees (contract employees, part-time employees, and dispatched workers).
Temporary employee headcount is based on the annual average.

Capital Allocation（6-Year Total）

FUJIMI INCORPORATED

- Achieve a long-term balance between strategic investments and shareholder returns by strengthening operating cash flow generation and making financing decisions considering the cost of capital, while investing to meet growing demand and drive medium- to long-term growth.

Financing
JPY 50 billion

Operating Cash Flow
JPY 130 billion

Cash and Cash Equivalents on Hand
JPY 7 billion

Shareholder Returns
JPY 50 billion

Capital Expenditures
JPY 130 billion

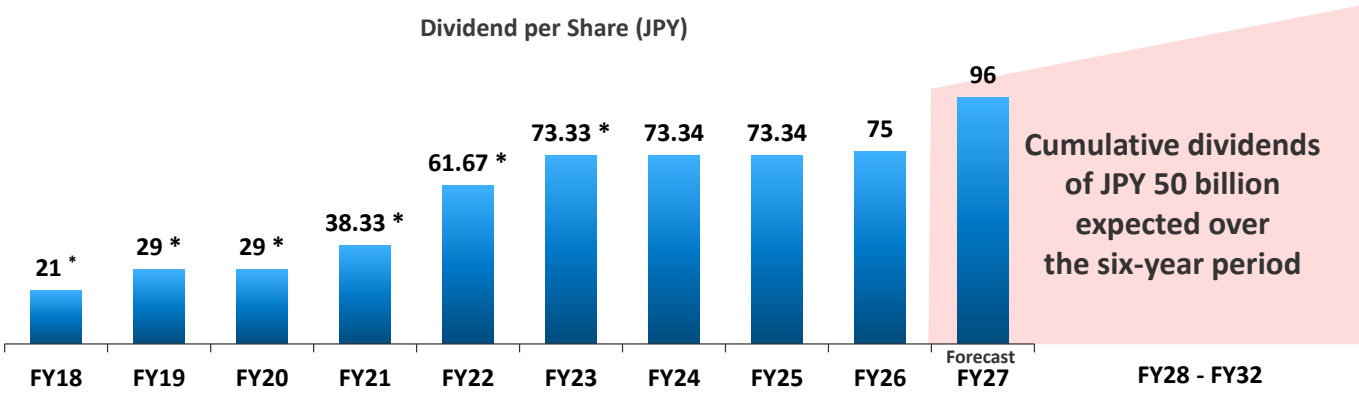
M&A Investments
JPY 7 billion

- **Dividend payout ratio of 55% or higher**
- **Progressive dividend policy maintained through FY2029**
- **Strategic investments to achieve medium- to long-term growth**
- **Expanding capacity to support strong near-term demand and future demand growth**
- **Creation of new businesses**
- **Strengthening of existing businesses**

Shareholder Returns

FUJIMI INCORPORATED

- Target a consolidated dividend payout ratio of 55% or higher through proactive shareholder returns linked to business performance.
- Maintain or increase dividends under a progressive dividend policy through FY2029.
- Explore ways to balance sustainable growth through investment with long-term shareholder returns from FY2030 onward.



	FY18	FY19	FY20	FY21	FY22	FY23	FY24	FY25	FY26	FY27	FY28 - FY32
Dividend Payout Ratio (%)	39.0	51.6	50.3	50.7	49.9	51.4	83.7	57.7	61.4	55.0	≧ 55%

*The Company conducted a 3-for-1 stock split effective July 1, 2023. Dividends per share for FY2023 and earlier have been adjusted retrospectively to reflect the stock split.

技術を磨き、心をつなぐ

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